

Quad 2-Input Exclusive-OR Gate

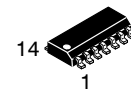
74AC86

General Description

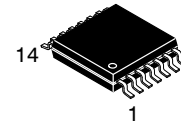
The 74AC86 contains four, 2-input exclusive-OR gates.

Features

- I_{CC} Reduced by 50%
- Outputs Source/Sink 24 mA
- These Devices are Pb-Free, Halide Free and are RoHS Compliant



SOIC14
CASE 751EF



TSSOP-14 WB
CASE 948G

ABSOLUTE MAXIMUM RATINGS

| Parameter | Symbol | Value | Unit |
|---|-----------------------|---------------------------|--------------------|
| Supply Voltage | V_{CC} | -0.5 to +6.5 | V |
| DC Input Diode Current $V_I = 0.5\text{ V}$ $V_I = V_{CC} + 0.5\text{ V}$ | I_{IK} | -20 +20 | mA |
| DC Input Voltage | V_I | -0.5 to $V_{CC} + 0.5$ | V |
| DC Output Diode Current $V_O = -0.5\text{ V}$ $V_O = V_{CC} + 0.5\text{ V}$ | I_{OK} | -20 +20 | mA |
| DC Output Voltage | V_O | -0.5 to $V_{CC} + 0.5$ | V |
| DC Output Source or Sink Current | I_O | ± 50 | mA |
| DC V_{CC} or Ground Current per Output Pin | I_{CC} or I_{GND} | ± 50 | mA |
| Storage Temperature | T_{STG} | -65 to +150 | $^{\circ}\text{C}$ |
| Junction Temperature (PDIP) | T_J | 140 | $^{\circ}\text{C}$ |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

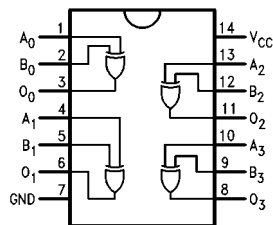


Figure 1. Connection Diagram

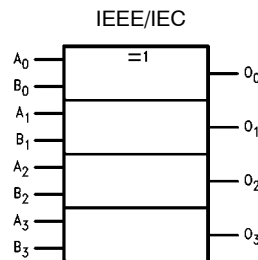
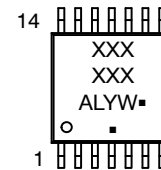
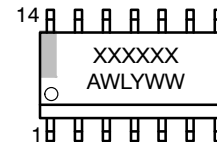


Figure 2. Logic Symbol

MARKING DIAGRAMS



- AC86 = Specific Device Code
- A = Assembly Location
- L, WL = Wafer Lot
- Y = Year
- W, WW = Work Week
- = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 3 of this data sheet.

PIN DESCRIPTION

| Pin Names | Description |
|---------------|-------------|
| A_0 - A_3 | Inputs |
| B_0 - B_3 | Inputs |
| O_0 - O_3 | Outputs |

RECOMMENDED OPERATING CONDITIONS

| Symbol | Parameter | Min | Max | Unit |
|---------------------|--|-----|----------|-------|
| V_{CC} | Supply Voltage | 2.0 | 6.0 | V |
| V_I | Input Voltage | 0 | V_{CC} | V |
| V_O | Output Voltage | 0 | V_{CC} | V |
| T_A | Operating Temperature | -40 | 85 | °C |
| $\Delta V/\Delta t$ | Minimum Input Edge Rate V_{IN} from 30% to 70% V_{CC} V_{CC} @ 3.3 V, 4.5 V, 5.5 V | 125 | | mV/ns |

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

DC ELECTRICAL CHARACTERISTICS

| Symbol | Parameter | V_{CC} (V) | $T_A = +25^\circ\text{C}$ | | $T_A = -40^\circ\text{C to } +85^\circ\text{C}$ | | Unit | Conditions |
|----------------------|--|-----------------|---------------------------|-------------------|---|---------------|--|--|
| | | | Typ | Guaranteed Limits | | | | |
| V_{IH} | Minimum High Level Input Voltage | 3.0 | 1.5 | 2.1 | 2.1 | V | $V_{OUT} = 0.1\text{ V}$ or $V_{CC} - 0.1\text{ V}$ | |
| | | 4.5 | 2.25 | 3.15 | 3.15 | | | |
| | | 5.5 | 2.75 | 3.85 | 3.85 | | | |
| V_{IL} | Maximum Low Level Input Voltage | 3.0 | 1.5 | 0.9 | 0.9 | V | $V_{OUT} = 0.1\text{ V}$ or $V_{CC} - 0.1\text{ V}$ | |
| | | 4.5 | 2.25 | 1.35 | 1.35 | | | |
| | | 5.5 | 2.75 | 1.65 | 1.65 | | | |
| V_{OH} | Minimum High Level Output Voltage | 3.0 | 2.99 | 2.9 | 2.9 | V | $I_{OUT} = -50\ \mu\text{A}$ | |
| | | 4.5 | 4.49 | 4.4 | 4.4 | | | |
| | | 5.5 | 5.49 | 5.4 | 5.4 | | | |
| | | | 3.0 | - | 2.56 | 2.46 | V | $V_{IN} = V_{IL}$ or V_{IH} $I_{OH} = -12\text{ mA}$ $I_{OH} = -24\text{ mA}$ $I_{OH} = -24\text{ mA}$ (Note 1) |
| | | | 4.5 | - | 3.86 | 3.76 | | |
| | | | 5.5 | - | 4.86 | 4.76 | | |
| V_{OL} | Maximum Low Level Output Voltage | 3.0 | 0.002 | 0.1 | 0.1 | V | $I_{OUT} = 50\ \mu\text{A}$ | |
| | | 4.5 | 0.001 | 0.1 | 0.1 | | | |
| | | 5.5 | 0.001 | 0.1 | 0.1 | | | |
| | | | 3.0 | - | 0.36 | 0.44 | V | $V_{IN} = V_{IL}$ or V_{IH} $I_{OL} = 12\text{ mA}$ $I_{OL} = 24\text{ mA}$ $I_{OL} = 24\text{ mA}$ (Note 1) |
| | | | 4.5 | - | 0.36 | 0.44 | | |
| | | | 5.5 | - | 0.36 | 0.44 | | |
| I_{IN} (Note 3) | Maximum Input Leakage Current | 5.5 | - | ± 0.1 | ± 1.0 | μA | $V_I = V_{CC}, \text{GND}$ | |
| I_{OLD} | Minimum Dynamic Output Current (Note 2) | 5.5 | - | - | 75 | mA | $V_{OLD} = 1.65\text{ V Max}$ | |
| I_{OHD} | | 5.5 | - | - | -75 | mA | $V_{OHD} = 3.85\text{ V Min}$ | |
| I_{CC} (Note 3) | Maximum Quiescent Supply Current | 5.5 | - | 2.0 | 20.0 | μA | $V_{IN} = V_{CC}$ or GND | |

1. All outputs loaded; thresholds on input associated with output under test.
2. Maximum test duration 2.0 ms, one output loaded at a time.
3. I_{IN} and I_{CC} @ 3.0 V are guaranteed to be less than or equal to the respective limit @ 5.5 V V_{CC} .

74AC86

AC ELECTRICAL CHARACTERISTICS

| Symbol | Parameter | V _{CC} * (V) | T _A = +25°C C _L = 50 pF | | | T _A = -40°C to +85°C C _L = 40 pF | | Unit |
|------------------|--|--------------------------|--|-----|------|---|------|------|
| | | | Min | Typ | Max | Min | Max | |
| t _{PHL} | Propagation Delay Inputs to Outputs | 3.3 | 2.0 | 6.0 | 11.5 | 1.5 | 12.5 | ns |
| | | 5.0 | 1.5 | 4.5 | 8.5 | 1.0 | 9.5 | |
| t _{PLH} | Propagation Delay Inputs to Outputs | 3.3 | 2.0 | 6.5 | 11.5 | 1.5 | 12.5 | ns |
| | | 5.0 | 1.5 | 4.5 | 8.5 | 1.0 | 9.0 | |

*Voltage Range 3.3 V is 3.3 V ±0.3 V.
Voltage Range 5.0 V is 5.0 V ±0.5 V.

CAPACITANCE

| Symbol | Parameter | Typ | Unit | Conditions |
|-----------------|-------------------------------|-----|------|-------------------------|
| C _{IN} | Input Capacitance | 4.5 | pF | V _{CC} = OPEN |
| C _{PD} | Power Dissipation Capacitance | 35 | pF | V _{CC} = 5.0 V |

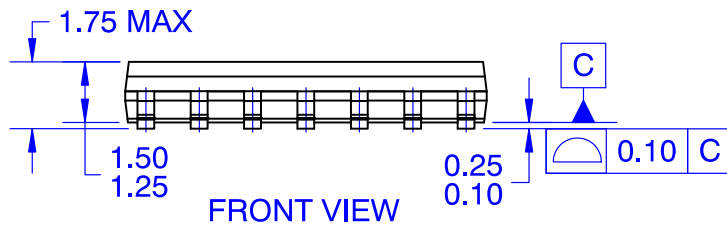
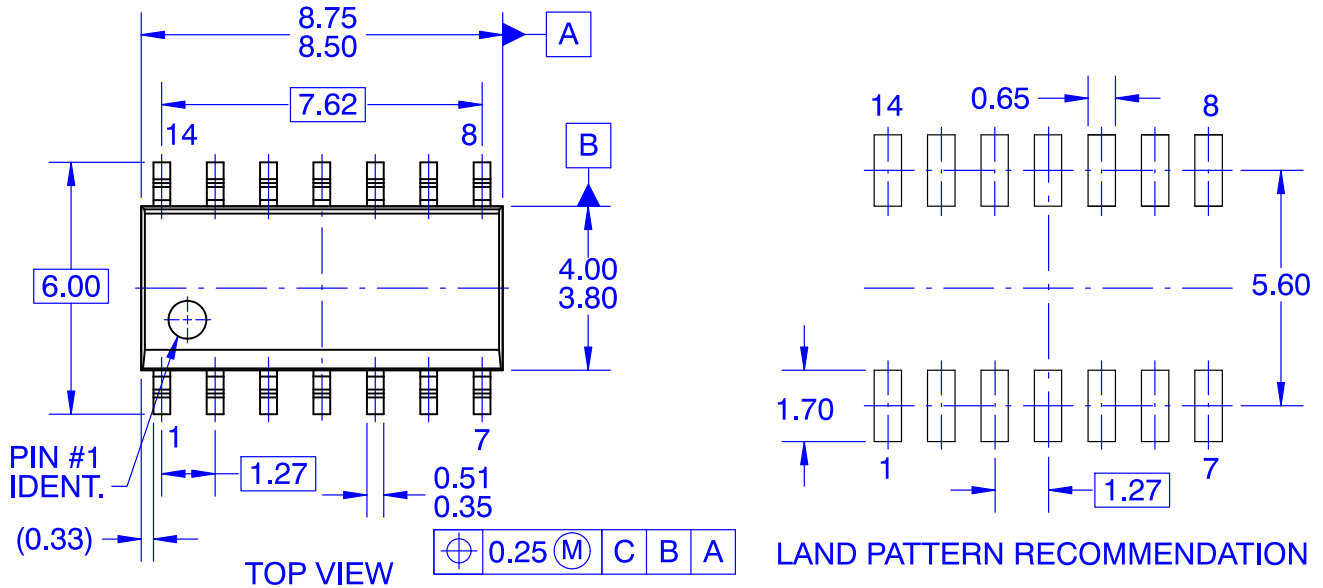
ORDERING INFORMATION

| Device | Marking | Package | Shipping [†] |
|------------|----------|----------|--------------------------|
| 74AC86MTCX | AC 86 | TSSOP-14 | 2500 Units / Tape & Reel |
| 74AC86SCX | AC86 | SOIC-14 | 2500 Units / Tape & Reel |

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

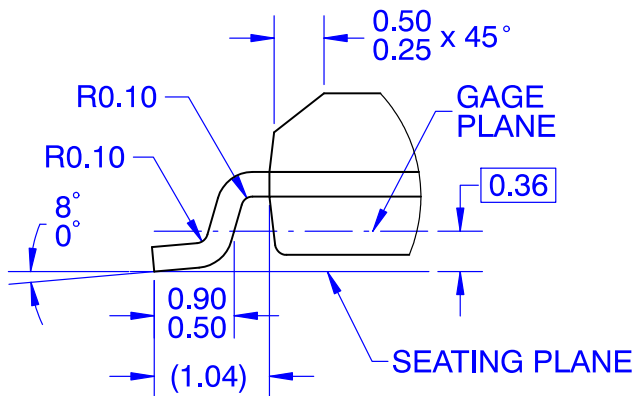
SOIC14
CASE 751EF
ISSUE O

DATE 30 SEP 2016



NOTES:

- A. CONFORMS TO JEDEC MS-012, VARIATION AB, ISSUE C
- B. ALL DIMENSIONS ARE IN MILLIMETERS
- C. DIMENSIONS DO NOT INCLUDE MOLD FLASH OR BURRS
- D. LAND PATTERN STANDARD: SOIC127P600X145-14M
- E. CONFORMS TO ASME Y14.5M, 2009



DETAIL A
SCALE 16 : 1

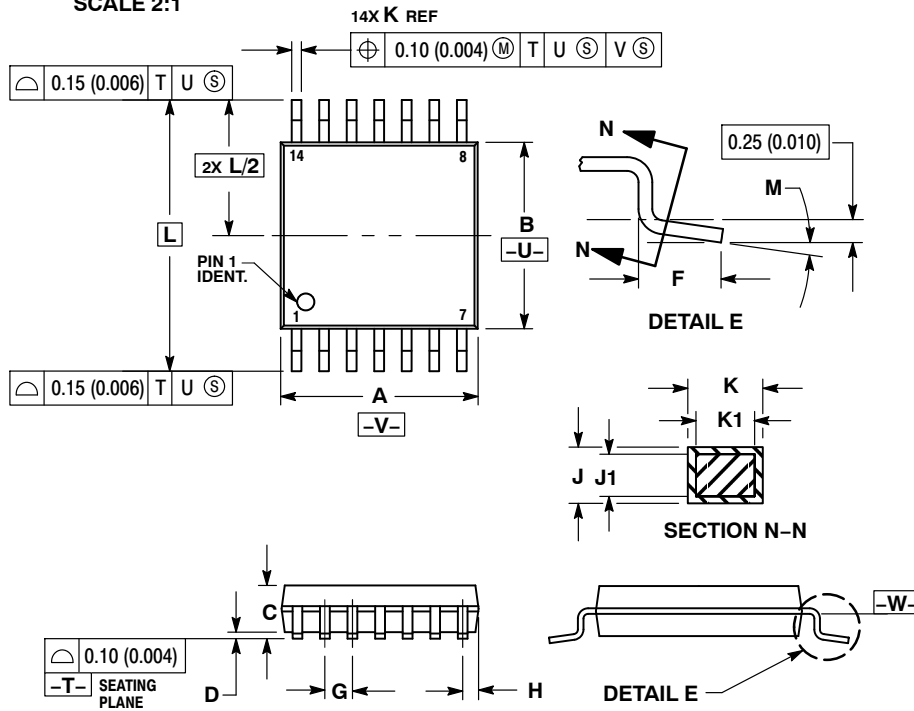
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TSSOP-14 WB
CASE 948G
ISSUE C

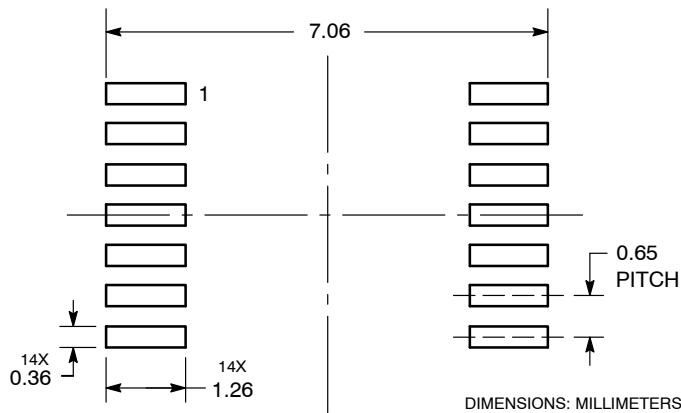
DATE 17 FEB 2016



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
 4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
 5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
 6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
 7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

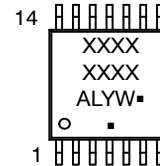
| DIM | MILLIMETERS | | INCHES | |
|-----|-------------|------|-----------|-------|
| | MIN | MAX | MIN | MAX |
| A | 4.90 | 5.10 | 0.193 | 0.200 |
| B | 4.30 | 4.50 | 0.169 | 0.177 |
| C | --- | 1.20 | --- | 0.047 |
| D | 0.05 | 0.15 | 0.002 | 0.006 |
| F | 0.50 | 0.75 | 0.020 | 0.030 |
| G | 0.65 BSC | | 0.026 BSC | |
| H | 0.50 | 0.60 | 0.020 | 0.024 |
| J | 0.09 | 0.20 | 0.004 | 0.008 |
| J1 | 0.09 | 0.16 | 0.004 | 0.006 |
| K | 0.19 | 0.30 | 0.007 | 0.012 |
| K1 | 0.19 | 0.25 | 0.007 | 0.010 |
| L | 6.40 BSC | | 0.252 BSC | |
| M | 0° | 8° | 0° | 8° |

RECOMMENDED
SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC
MARKING DIAGRAM*



- A = Assembly Location
- L = Wafer Lot
- Y = Year
- W = Work Week
- = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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